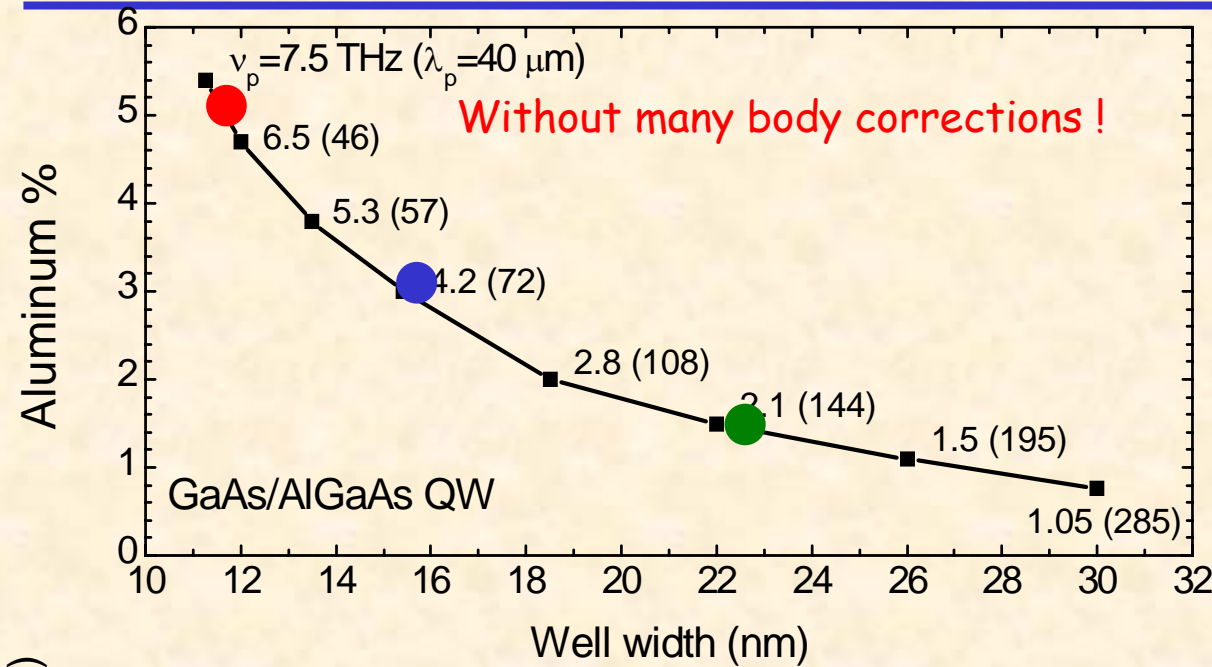

THz QWIP

h.c.liu@nrc.ca

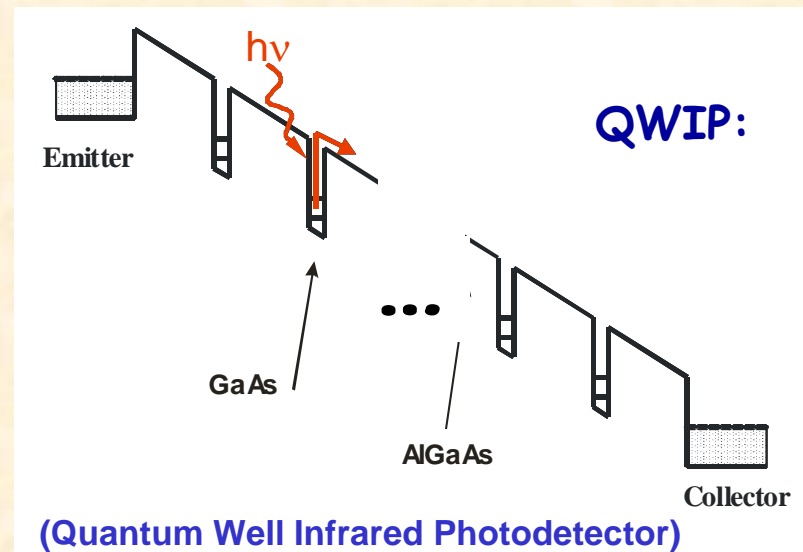
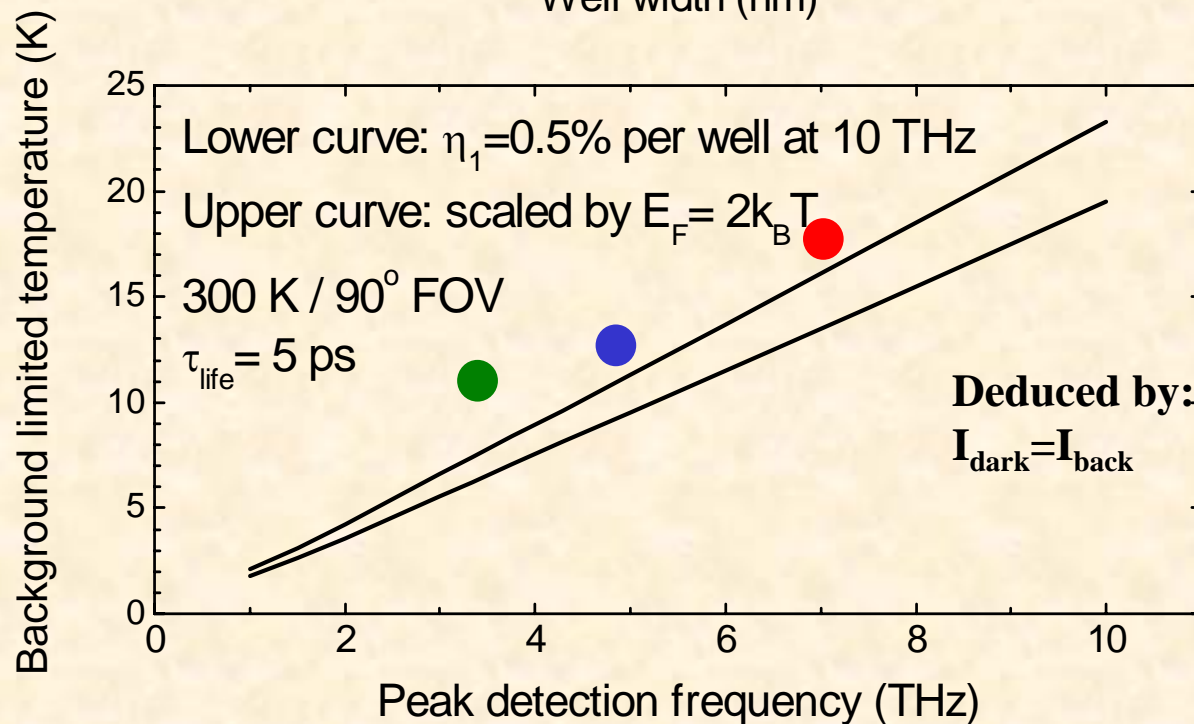
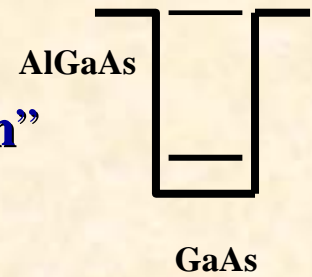
Terahertz quantum well photodetectors



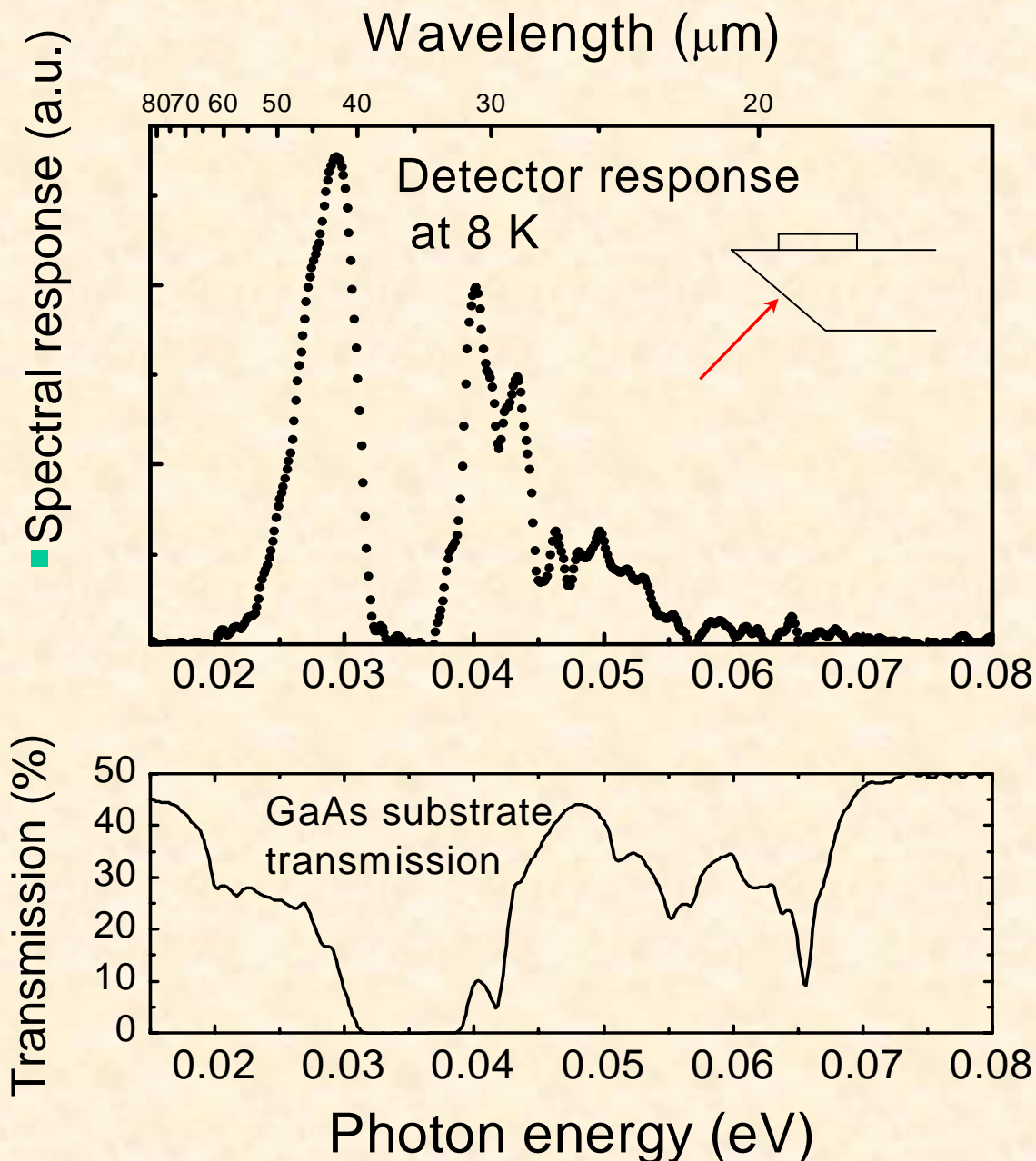
QWIP in the THz region:
Predicted/projected Performance

*H. C. Liu, H. Luo, C. Y. Song,
Z. R. Wasilewski, A. J. SpringThorpe
J. C. Cao*

“Optimal Design”



THz QWIP 1st experiment



50 QWs

12/40nm GaAs/AlGaAs

Si doping: $1E11\text{cm}^{-2}$

[Al]=5%

Bound-to-continuum or
phonon/polaron effect?

Noisy spectrum

45-deg facet geometry

P-polarized response

Optical phonon "dark" region

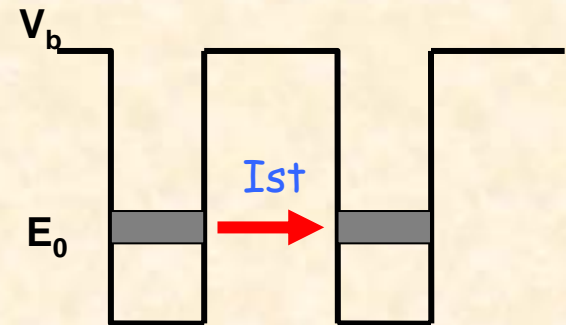
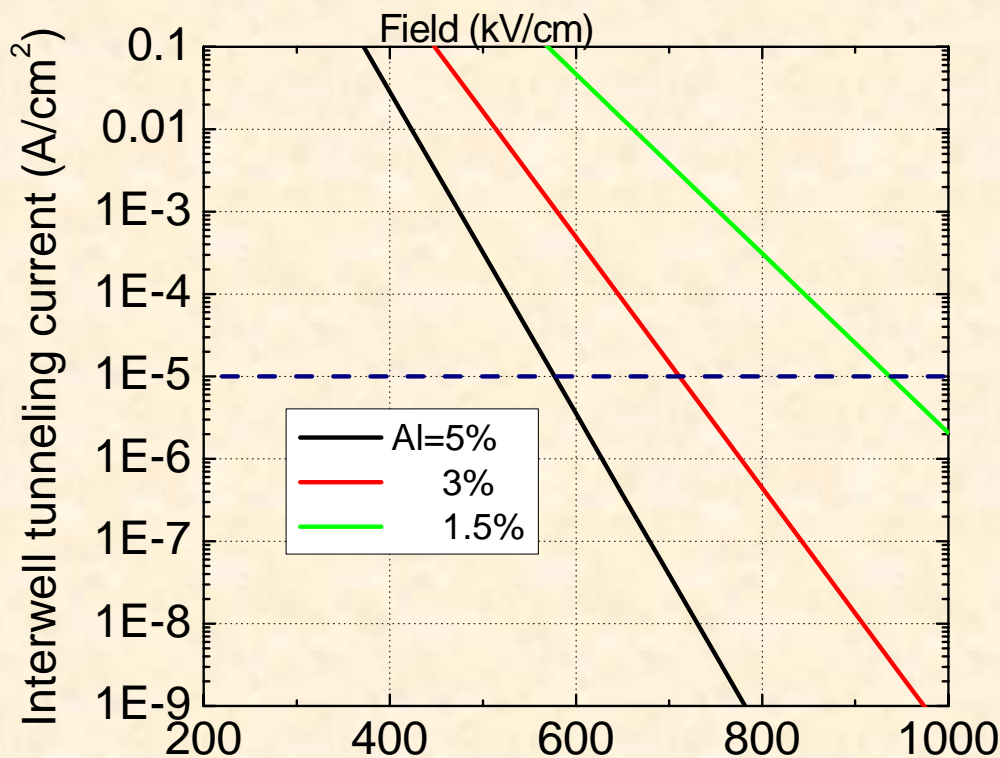
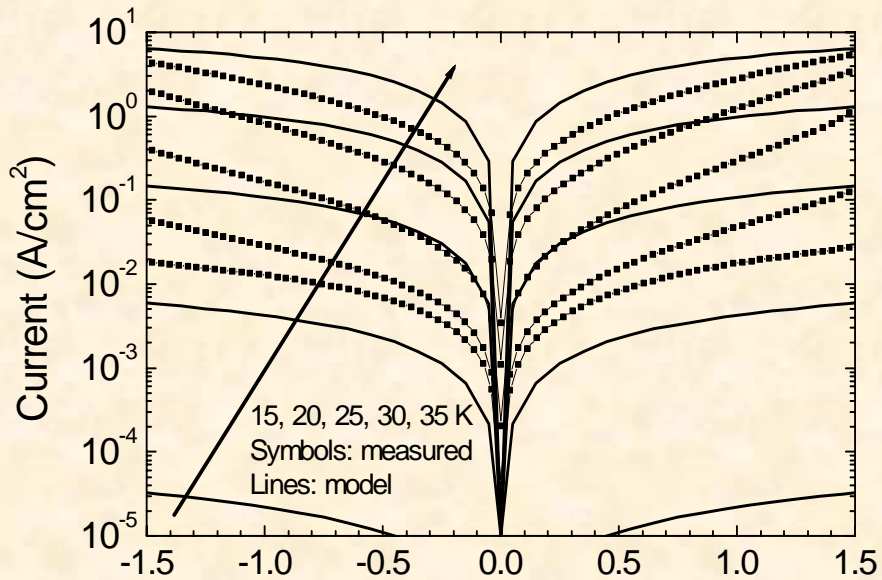
42meV - zone edge 2 phonon

45meV - AlAs-like phonon

Problem: high dark current & Inter-well sequential tunneling

➤ Dark current stops decreasing for $T < 20\text{K}$, $\sim 10^{-2} \text{ A/cm}^2$, no BLIP operation.

➤ Main cause of high dark current for this device: sequential inter-well tunneling.



$$j_{st} \sim \frac{qn_{2d}}{\tau_{st}}$$

$$= \frac{qn_{2d}v_0}{L_w} \exp\left\{-\frac{2\sqrt{2m^*(V_b - E_0)}}{\hbar} L_b\right\}$$

$$v_0 = \sqrt{\frac{2E_0}{m^*}}$$

THz QWIP Design (2nd Series)

THz QWIPs (2nd series)

Top contact 4000Å GaAs Si: 1E17cm⁻³

L_b AlGaAs (last barrier)

N repeats of

L_w GaAs well center 100Å doped with Si to Nd

L_b AlGaAs barrier

Bottom contact 8000Å GaAs Si: 1E17cm⁻³

GaAs undoped buffer

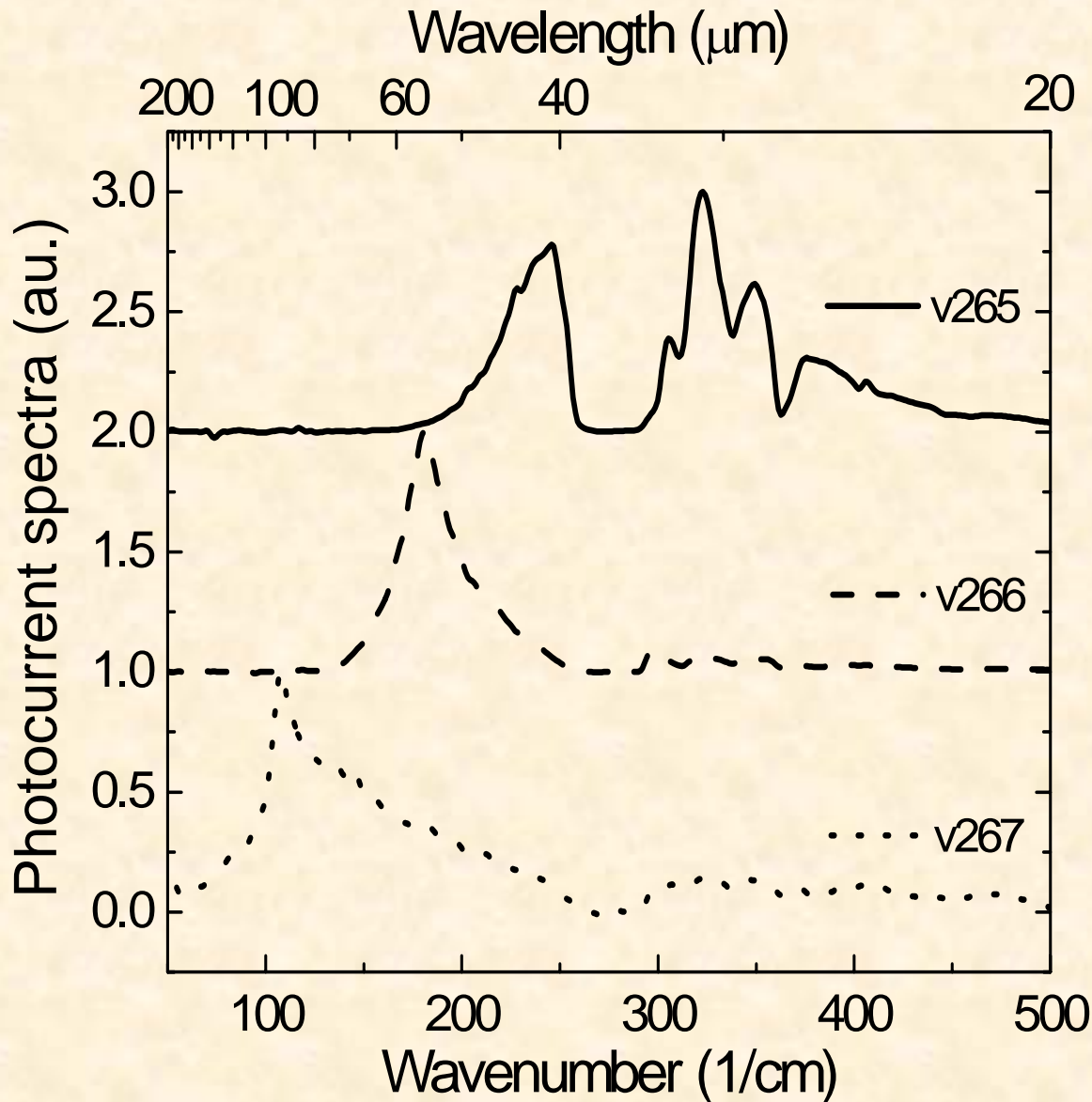
GaAs SI substrate

3 samples (for ~7, 4, 2 THz):

L _w (Å)	L _b (Å)	N	[Al]	Nd (cm ⁻³)
119	552	40	5%	1E17
155	702	30	3%	6E16
221	951	23	1.5%	3E16

- L_b: I_{st} ~ 10⁻⁵ A/cm², ~background I_{ph}
- Well doping for adequate peak absorption (1E11 ~ 3E10 cm⁻²) ~0.2% per well
- Low contact doping to reduce free carrier absorption (plasma ~ 90cm⁻¹)
- Total epilayer thickness ~ 3.5µm

Summary of Spectra



➤ Peak wavelength shorter than design -> many body effects

Sample	V0265	V0266	V0267
Wavenumber ($1/\text{cm}$)	290	180	108
Energy (mev)	36.0	22.4	13.4
Wavelength (μm)	34	56	93
Freq. (THz)	8.7	5.4	3.2
Design (THz)	6.5	3.8	1.9

↑ ↑ ↑ Peak position

Many body effects

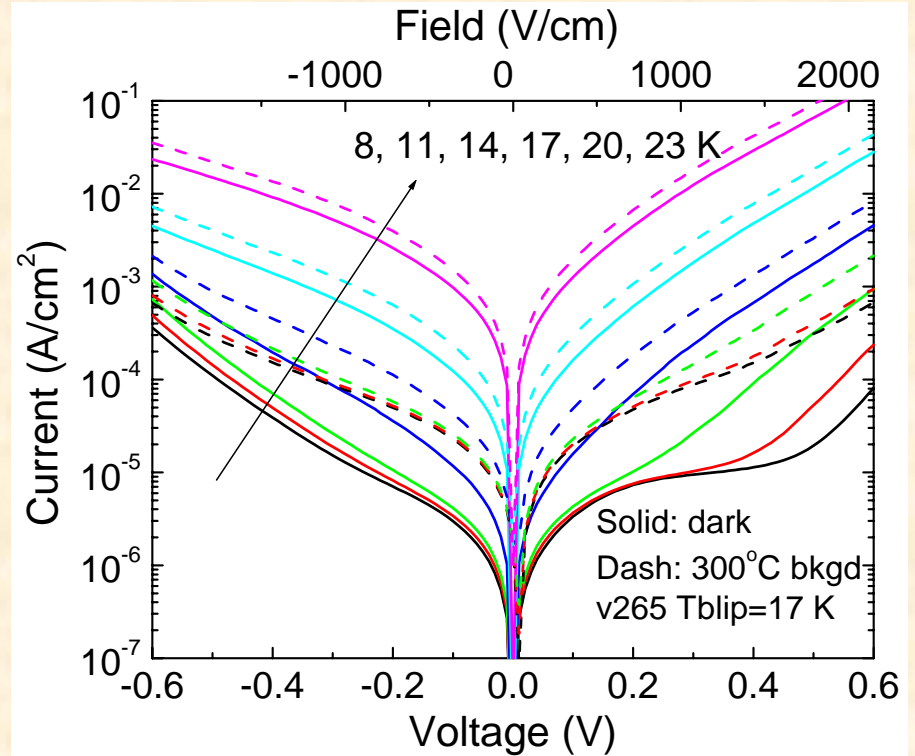
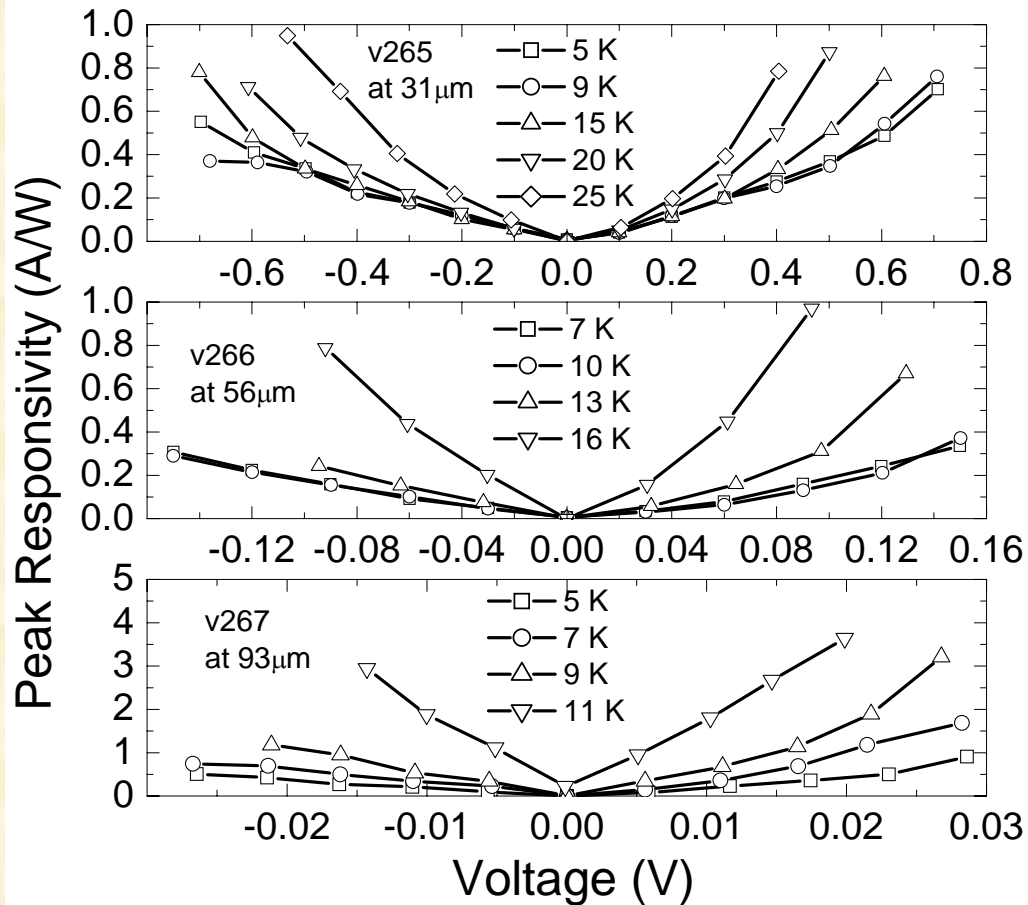
Device parameters

Wafer	L_w (nm)	L_b (nm)	N	[Al]	N_d (cm ⁻³)	n_{2D} (cm ⁻²)
V265	11.9	55.2	40	5%	1E17	1E11
V266	15.5	70.2	30	3%	6E16	6E10
V267	22.1	95.1	23	1.5%	3E16	3E10

Comparison

Wafer	E_1 (meV)	E_2 (meV)	$E_{\text{ex-co}}$ (meV)	E_{depol} (meV)	Theory peak (meV)	Exp peak (meV)
V265	14.31	43.21	4.71	2.2	35.81	~36
V266	8.58	26.93	3.65	1.6	23.60	22.3
V267	4.25	12.92	2.50	1.0	12.17	13.4

Background Limited IR performance



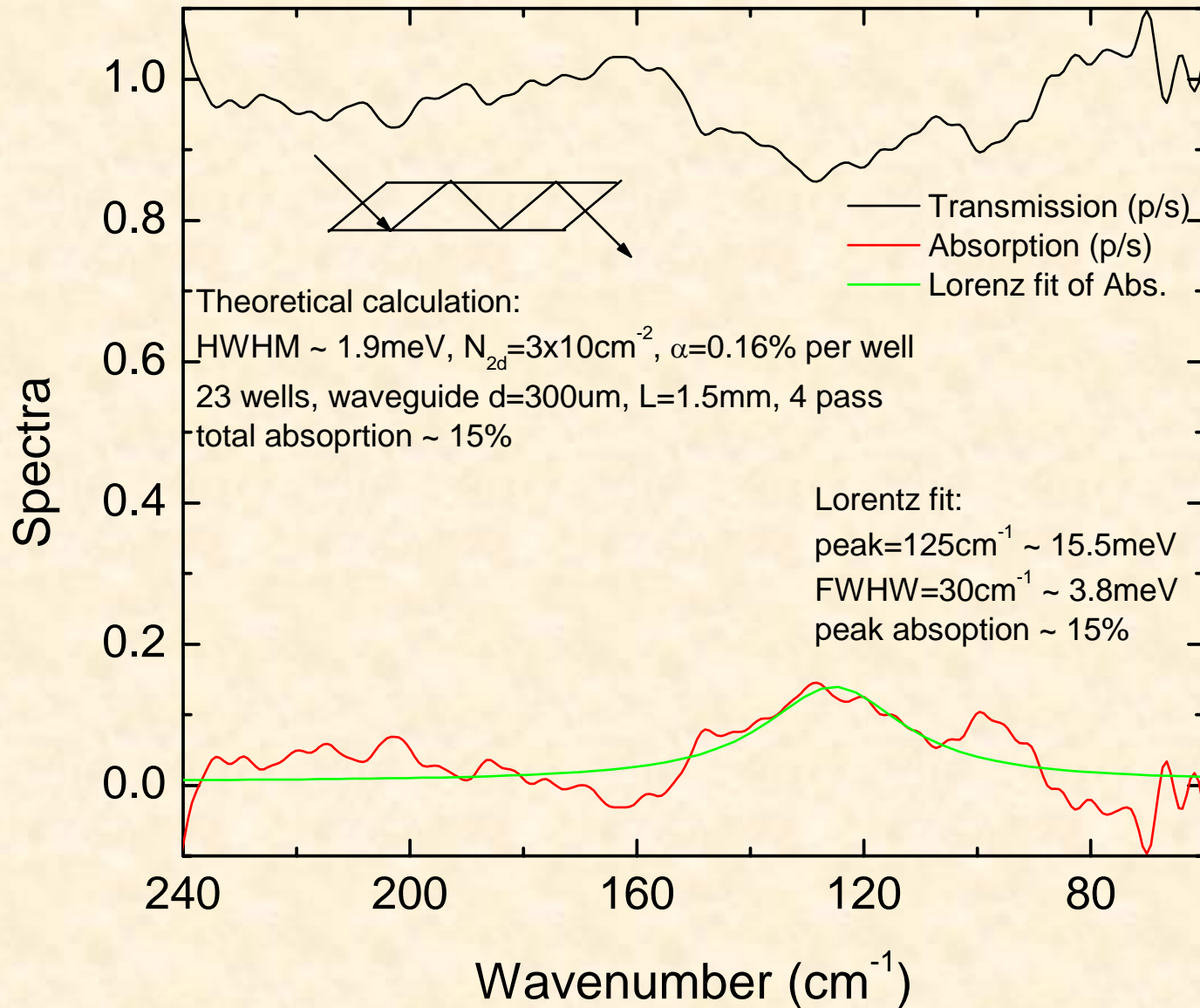
Summary

- Responsivity $R = 0.5 \sim 1$ A/W, similar to Mid-IR QWIP.
- Transition temperature correlates with BLIP temperature: 17, 13, 12 K

- ❑ Wider barrier can be employed to effectively reduce inter-well tunneling current and enable BLIP operation.
- ❑ BLIP was demonstrated at 17, 13, 12 K for peak response at 9, 5.4, 3.2 THz.

Future: Absorption needs to be improved

V267 THz QWIP absorption at room temperature



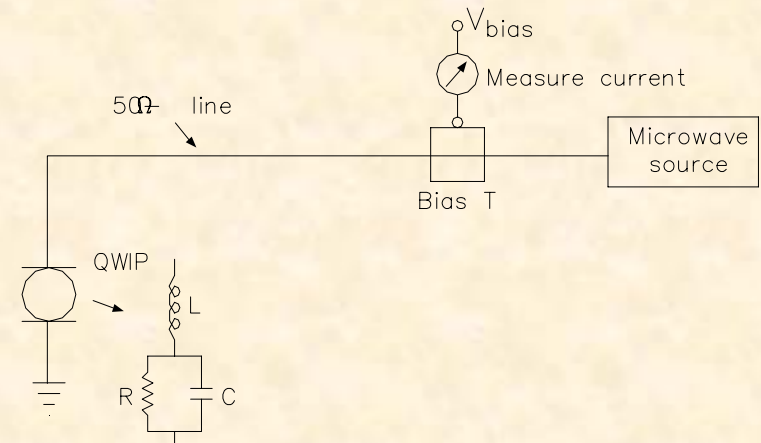
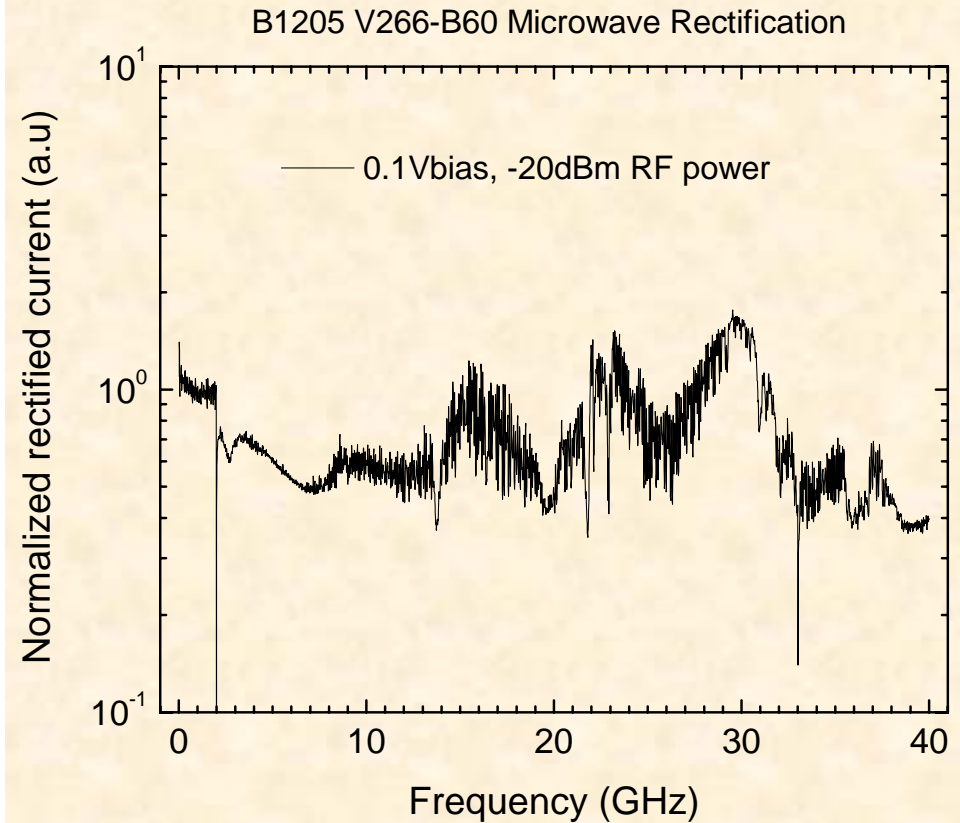
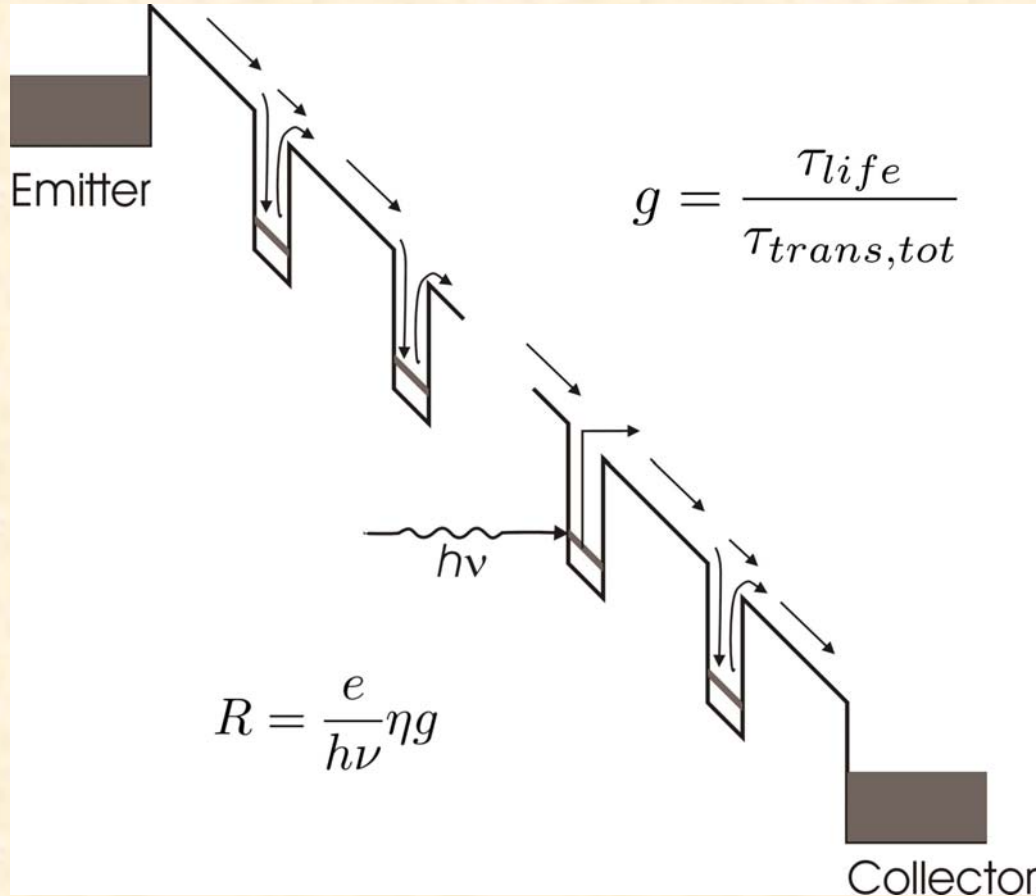
Absorption in our detector:
 $\sim 7.5\%$ for polarized light

On-going:
Improve absorption by

- Higher doping
- More wells

Goal: Absorption $> 50\%$

Future: High Speed Characteristics

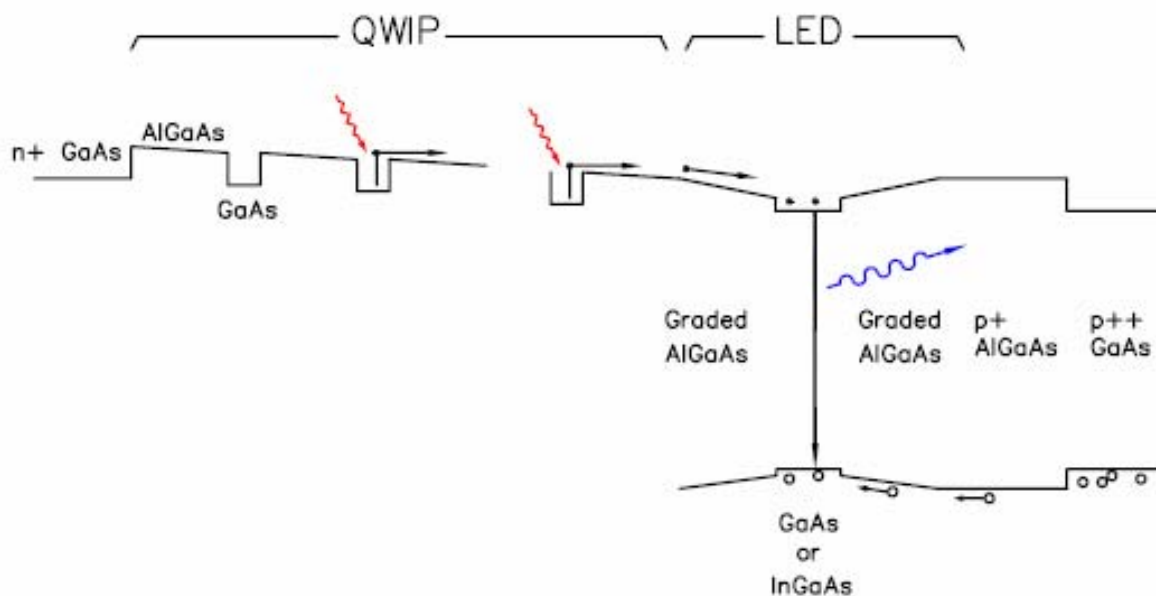


Goal: Flat response to 30 GHz

Application: THz heterodyne receiver

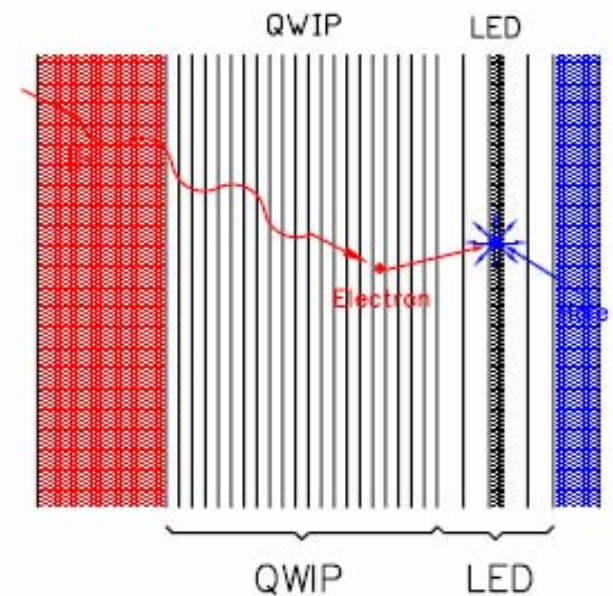
Future: THz Imaging Device

Long wavelength to near IR converter



Electron. Lett. 31, 832 (95)

QWIP-LED stack is thin
pixellation may not be
necessary



Key feature: thin active layer

Electron. Lett. 33, 378 (97)

Goal: Background limited performance imaging in THz region